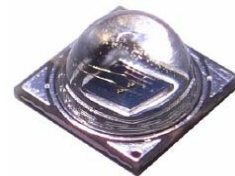


# Specification For IR Series

## HPL-H35CI1L1



### Features

- Dimension : 3.45mm(L)×3.45mm(W)
- High Radiant Flux type
- All Metal Design Cu Substrate with Silicone Lens
- Middle beam angle 90°
- Ultra low thermal resistance
- MSL Level : 3

### Applications

- Surveillance / CCTV
- Infrared Illumination for cameras
- Data Communication
- Machine vision

**RoHS**  
Compliant

5F, No 173-8, Yung-Fon Road, Tu-Cheng District, New Taipei City, Taiwan, R.O.C.  
TEL: +886-2-8262-8886 FAX : +886-2-8262-8885



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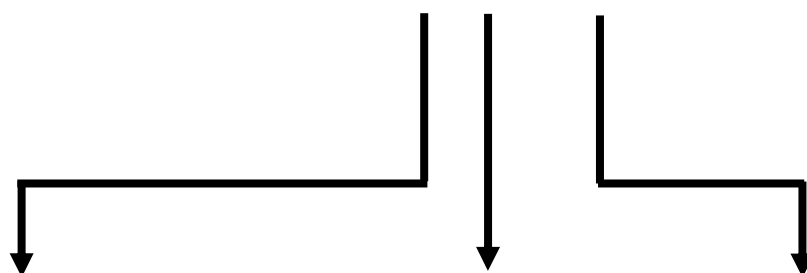
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## General Information

# HPL - H35CI1L1



**Beam Angle-**

Middle beam angle

**Wavelength-**

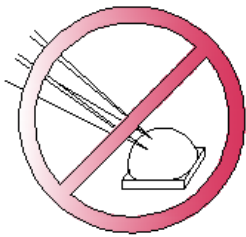
IR 730nm

**Power-**

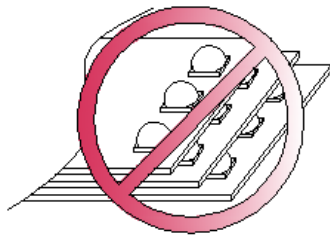
2 W

## Part Number Matrix

Wavelength \ Type	90°Lens	90°Lens & Star
IR 730	HPL-H35C11L1	HPL-H35UI1L1



Do not poke the Led Lens with sharp object



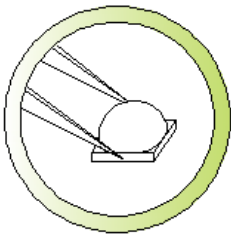
Do not stack assembled PCB



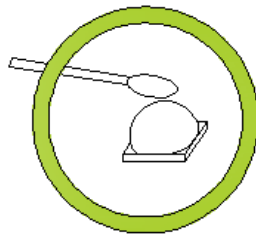
Do not hold the Led with hand



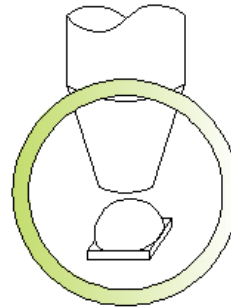
Do not press or push the Led Lens



Hold the Led only by the substrate



Clean the LED surface with cotton bud



Use pick and place nozzle per recommendation in data sheet

## Absolute Maximum Ratings

(T<sub>j</sub>=25°C)

Parameter	Symbol	Rating	Unit
Power Dissipation	P	1.9	W
Forward Current	I <sub>F</sub>	700	mA
Reverse Voltage	V <sub>R</sub>	5	V
LED Junction Temperature	T <sub>J</sub>	125	°C
Operating Temperature Range	T <sub>opr</sub>	- 40°C to + 85°C	
Storage Temperature Range	T <sub>stg</sub>	- 40°C to + 120°C	
Soldering Condition	T <sub>sol</sub>	260°C For 10 Seconds	

## Initial Electrical/Optical Characteristics

(T<sub>j</sub>=25°C)

Parameter	Symbol	Min	Typ	Max	Test Condition	Unit
Peak wavelength	λ <sub>p</sub>	730	-	750	I <sub>F</sub> = 700mA	nm
Radiant Flux	Φ <sub>e</sub>	350	580	-		mW
Radiant Intensity	I <sub>e</sub>	-	310	-		mW/Sr
Forward Voltage	V <sub>F</sub>	-	2.15	-		V
Spectra half-width	Δλ	-	25	-		nm
Beam Angle	2Θ <sub>1/2</sub>	-	90	-		deg
Temperature coefficient of brightness	TC <sub>I</sub>	-	-0.3	-	-	%/K
Temperature coefficient of voltage	TC <sub>V</sub>	-	-1	-	-	mV/K
Temperature coefficient of wavelength	TC <sub>λ</sub>	-	0.3	-	-	nm/K
Thermal Resistance, Junction-Case	R <sub>th, J-C1</sub>	-	5	-	-	°C/W

Note: 1. The thermal resistance value is measured with MCPCB (Star).

## Bin Code List for Reference

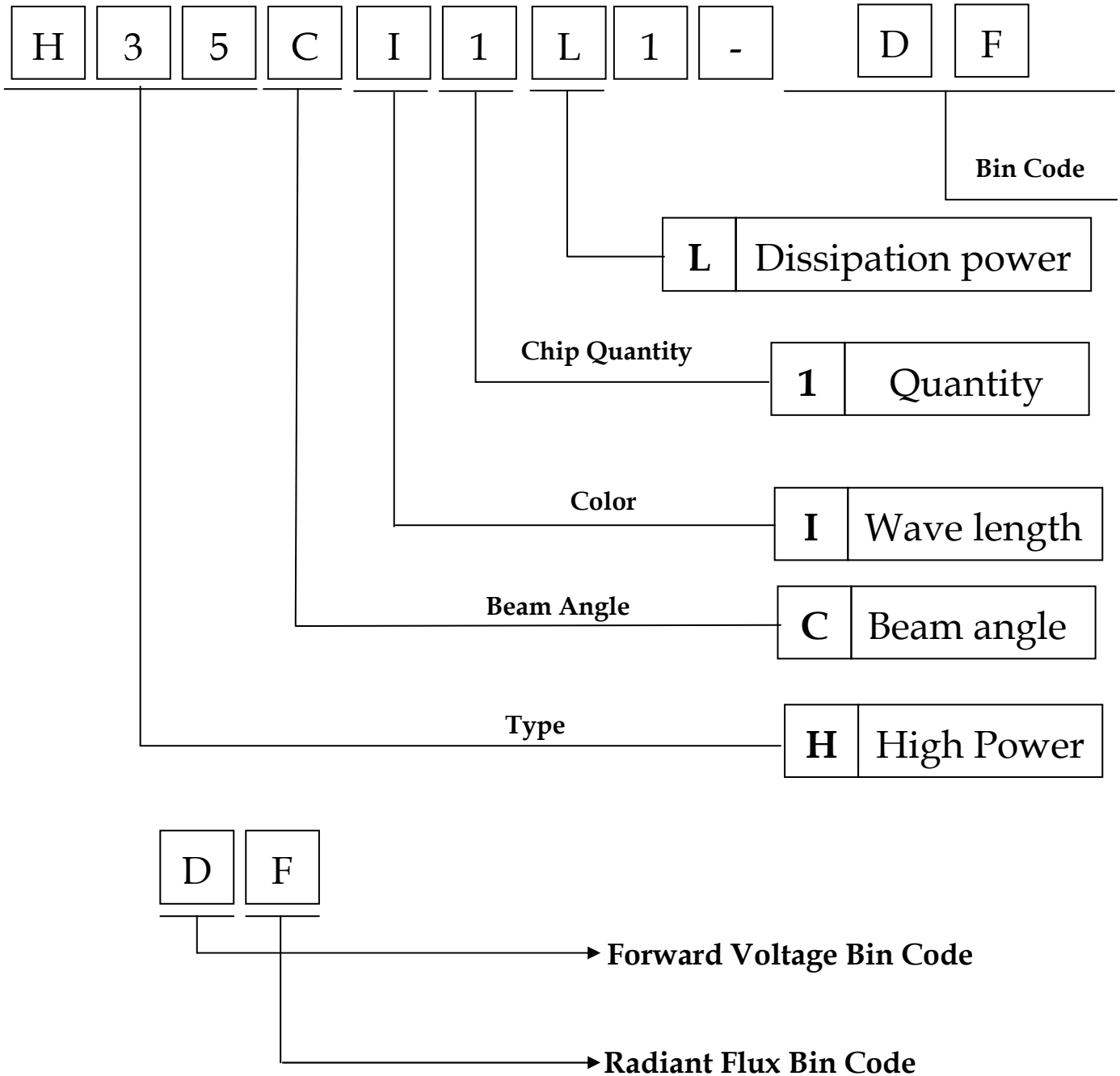
(T<sub>j</sub>=25°C)

Item	Bin Code	Symbol	Condition	Min.	Max.	Unit
Forward Voltage <sup>1</sup>	B	V <sub>F</sub>	I <sub>F</sub> = 700 [mA]	1.59	1.83	V
	C			1.83	2.07	
	D			2.07	2.31	
	E			2.31	2.55	
Radiant Flux <sup>2</sup>	D	Φ <sub>e</sub>	I <sub>F</sub> = 700 [mA]	350	425	mW
	E			425	500	
	F			500	600	
	G			600	700	

Note

1. Forward voltage measurement allowance is ± 0.1V.
2. Radiant flux measurement allowance is ± 10%.

## Part Number Formation



## Characteristic Diagram

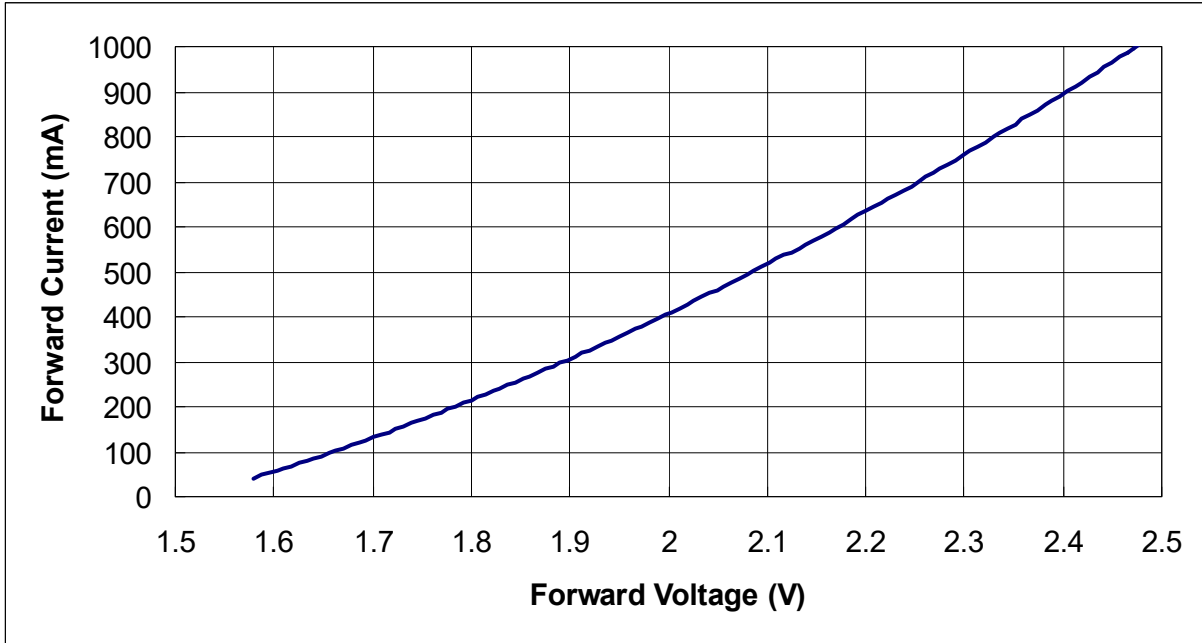


Fig. Forward Current vs. Forward Voltage

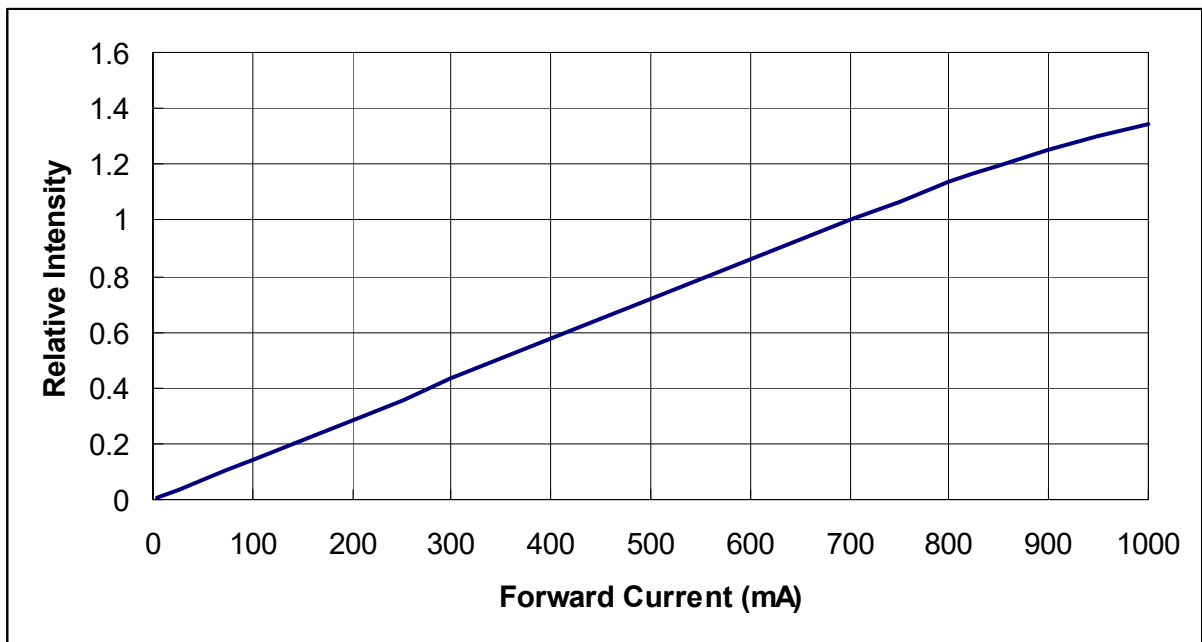


Fig. Relative Intensity vs. Forward Current



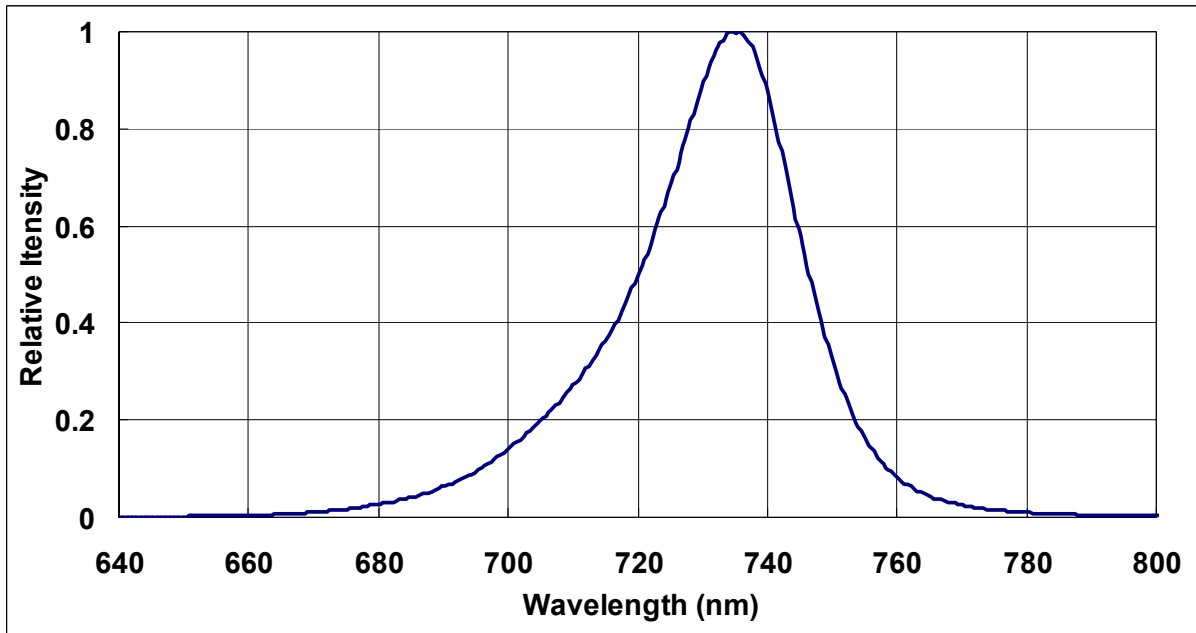


Fig. Typical Relative Intensity vs. wavelength

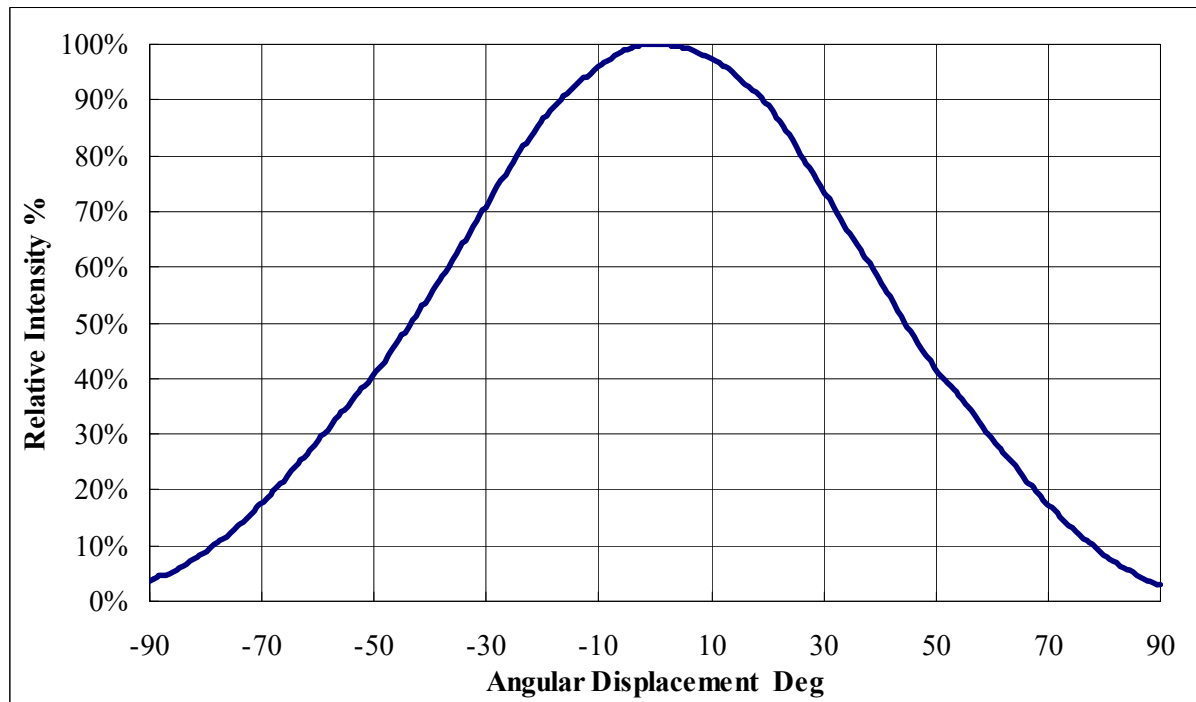


Fig. Typical Representative Spatial Radiation Pattern

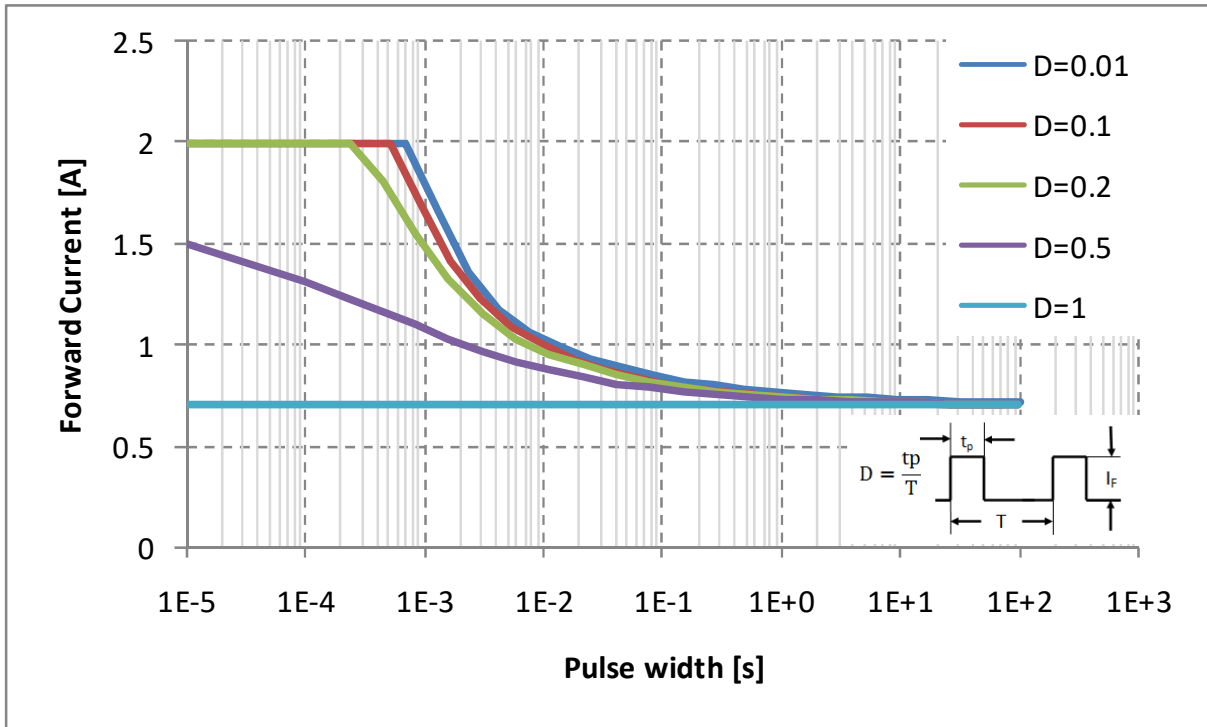


Fig. Permissible pulse handling capability at  $T_j=85^\circ\text{C}$  for various duty cycles (D)

**Outline Dimension**

Unit : mm

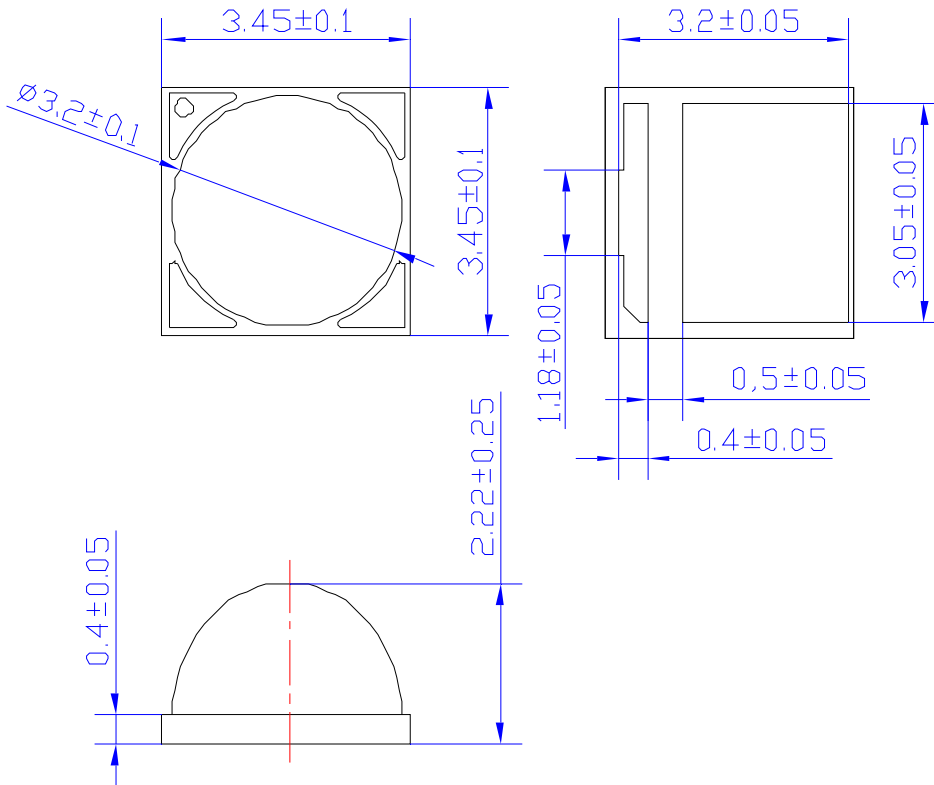
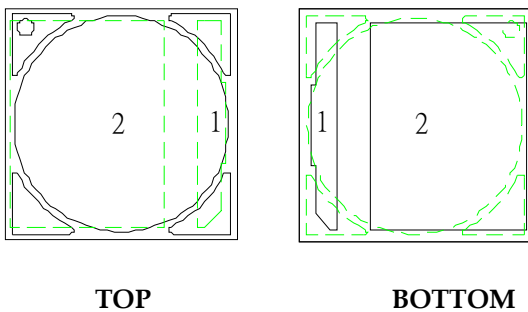


Fig. Package Outline Drawing.

● **Pad Configuration**



PAD	Function
1	Cathode
2	Anode、Thermal

Fig. Pad configuration.

Note: Please don't put conductive material on the top surface of LEDs.

## Recommended Solder Pattern

Unit : mm

Tolerance  $\pm 0.05$

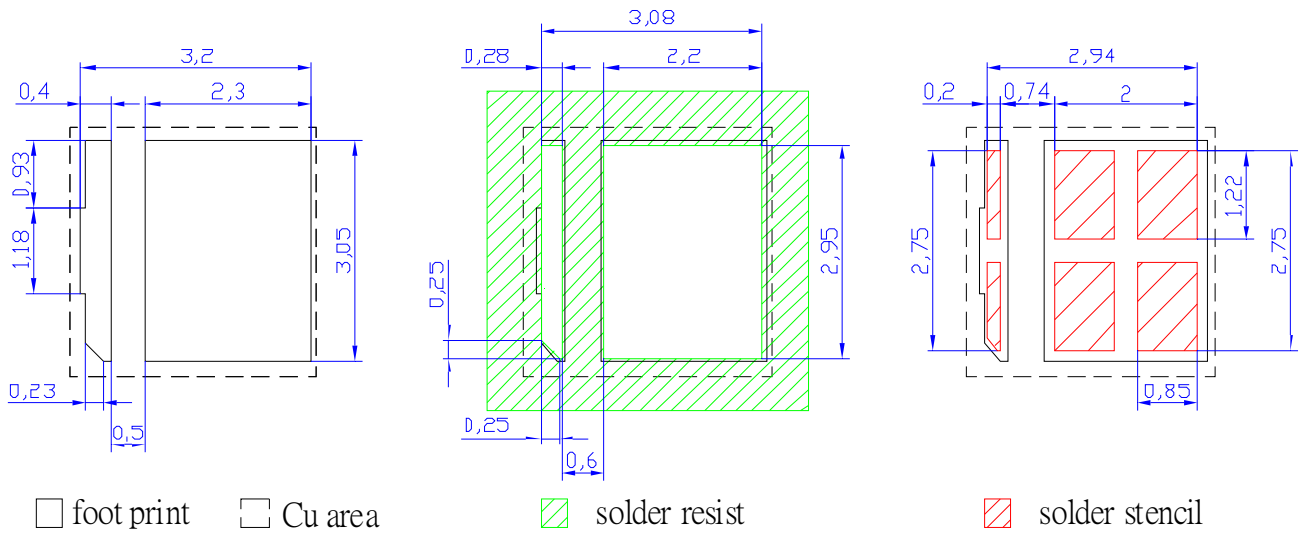


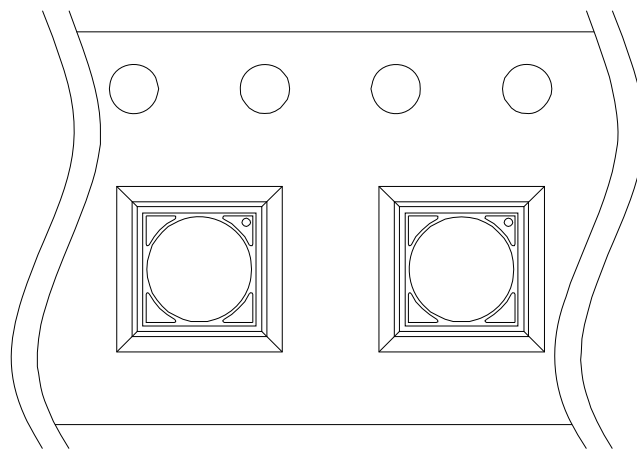
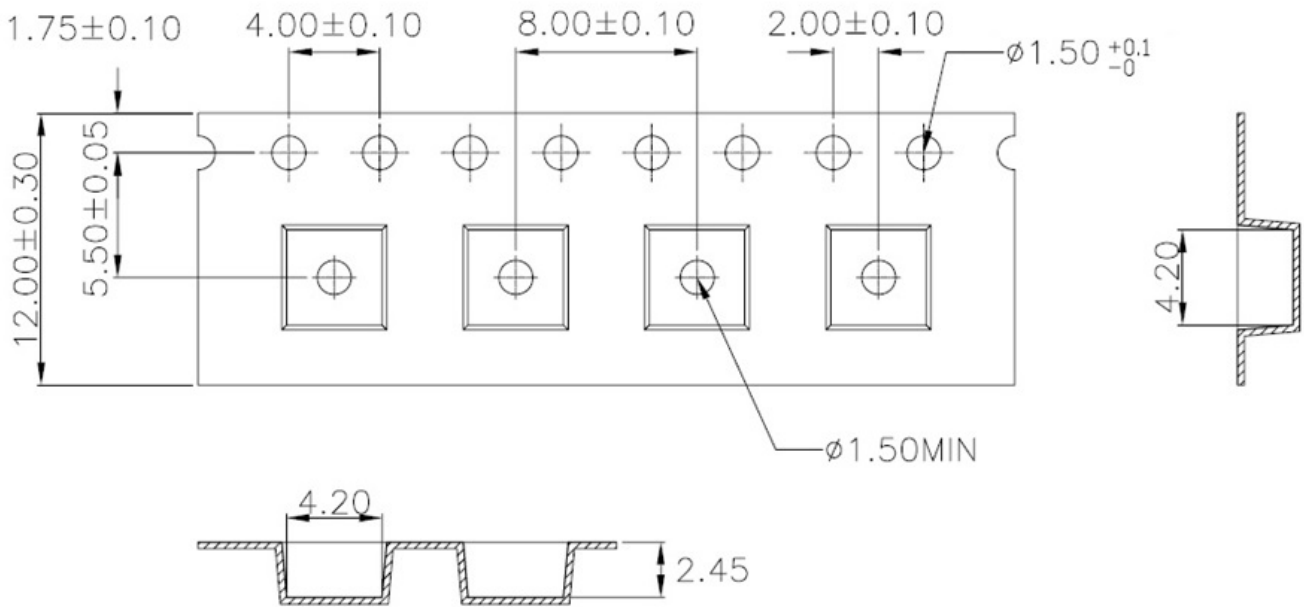
Fig. Solder Pad Layout.

## Shipping Package Style

### Tapping Dimension Packaging Specification

- Moisture proof bag.
- 1 Reel/bag.
- Q'ty : 2500(MAX)/Reel

Unit : mm



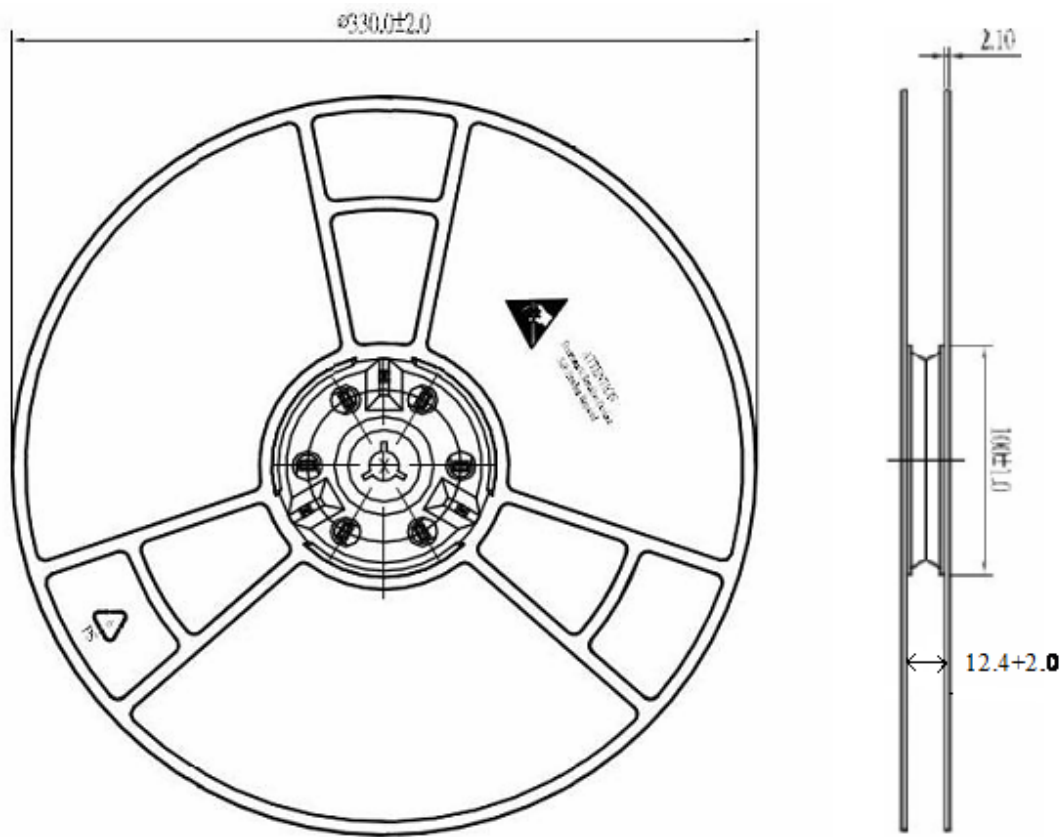
### 13 inch Reel Package

Box Type	Dimension (mm)	Reel/Box	Lens Type (Pcs)
Small Box(S)	415 x 380 x 95	5 Reel/Box	12500
Middle Box(M)	415 x 380 x 290	15 Reel/Box	37500
Large Box(L)	780 x 432 x 310	30 Reel/Box	75000

### Reel Packaging :

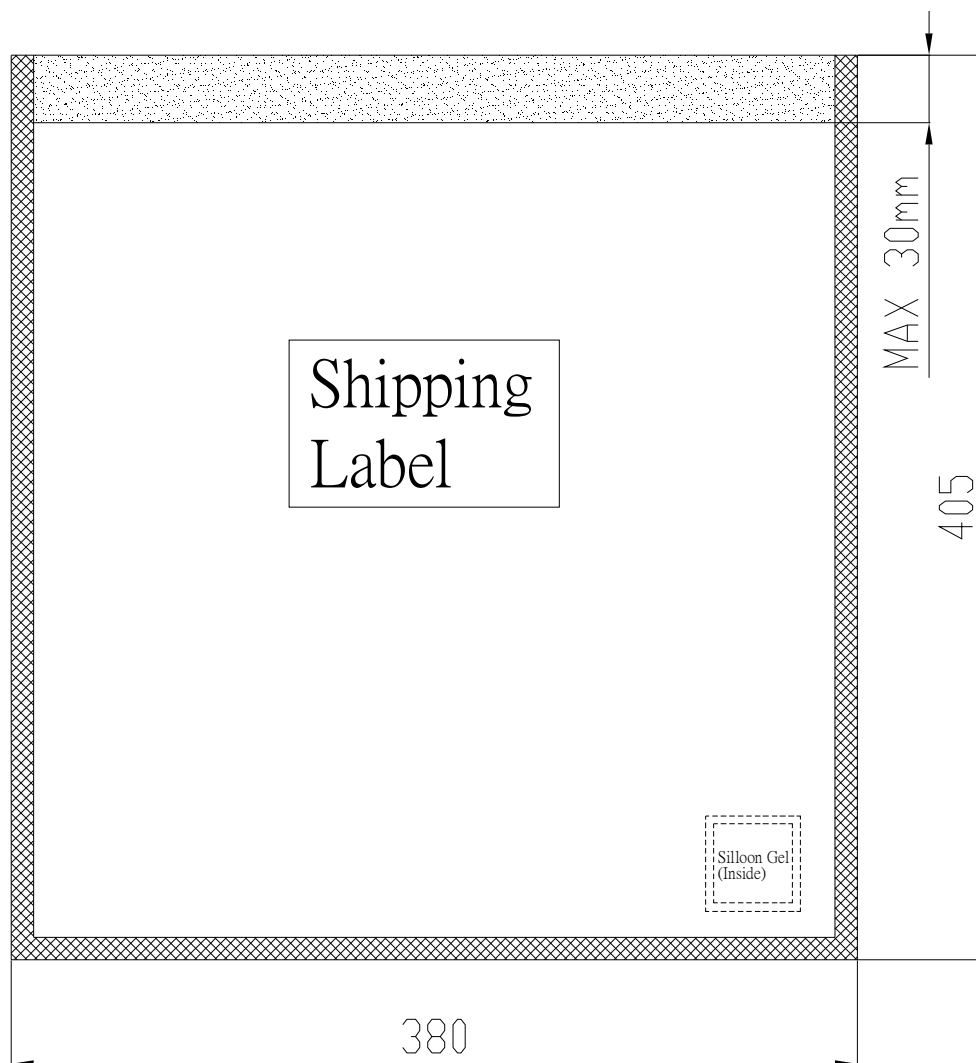
Reel Part :

Unit : mm



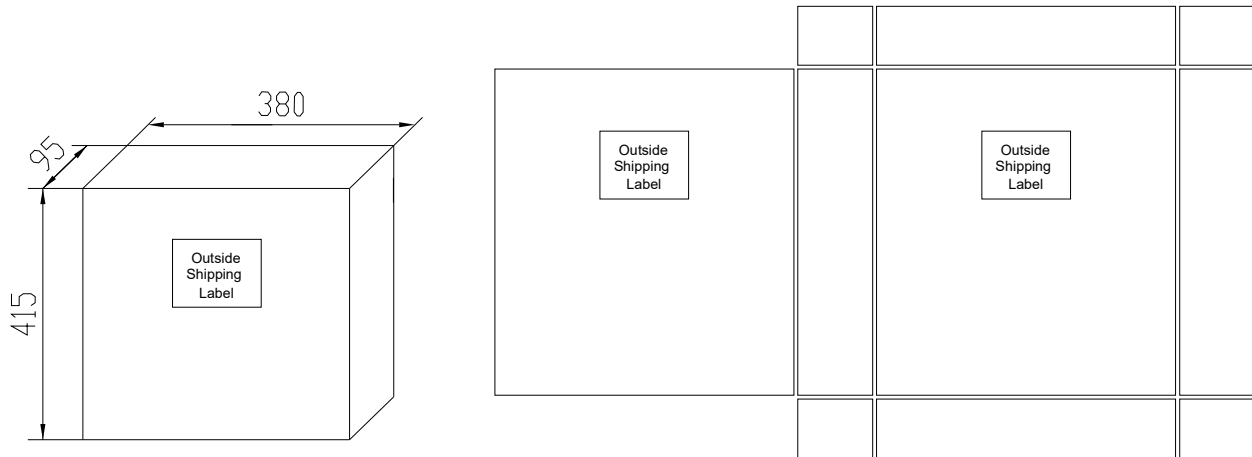
**Anti Static Bag :**

Unit : mm



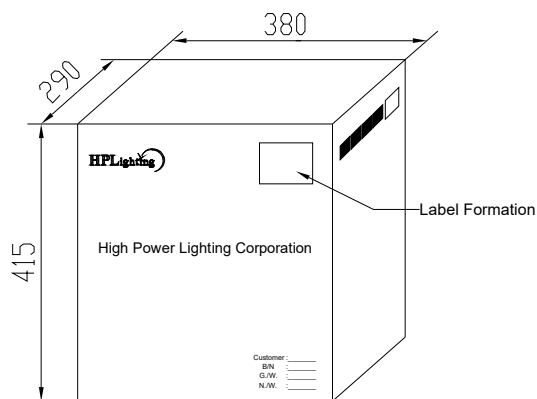
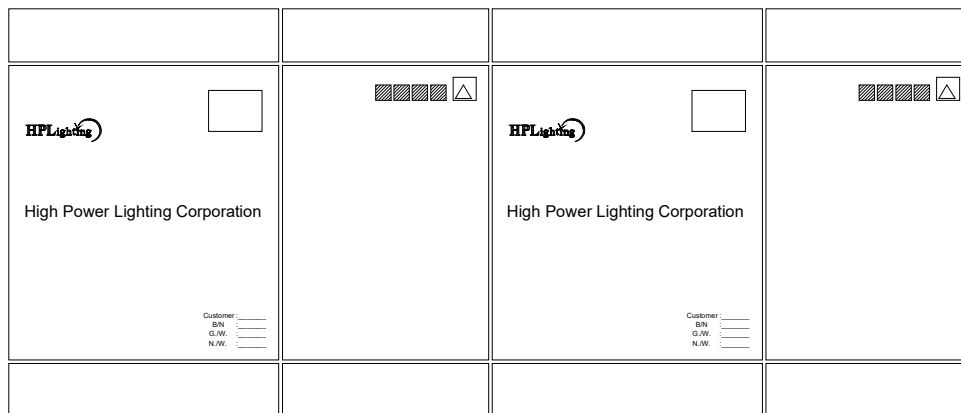
**Small Box**

Unit : mm



**Middle Box**

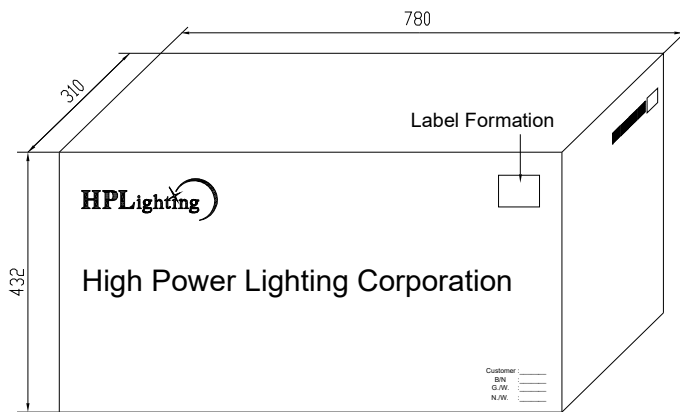
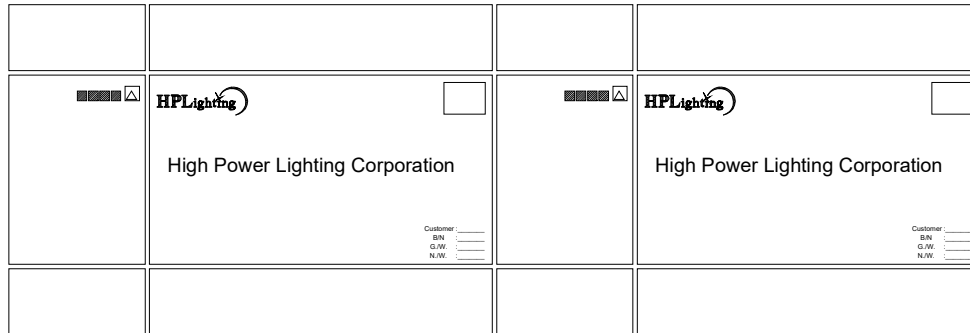
Unit : mm







Large Box

Unit : mm



### Label Formation

70mm

<b>HPLighting</b>	
P/N: XXXXXXXXXXXXXXXXX	BIN Rank: XXXXXXX
	
LOT: XXXXXXXXXXXXXXXXX	Q'ty: XXXXX pcs
	
High Power Lighting Corporation (Taiwan)	XXX

40mm

<b>HPLighting</b>	
Customer :XXXXXXXXXXXXXXXXXXXXXX	
P/N: XXXXXXXXXXXXXXXXX	
OQC Stamp:	Q'ty: XXXXX pcs
High Power Lighting Corporation (Taiwan)	

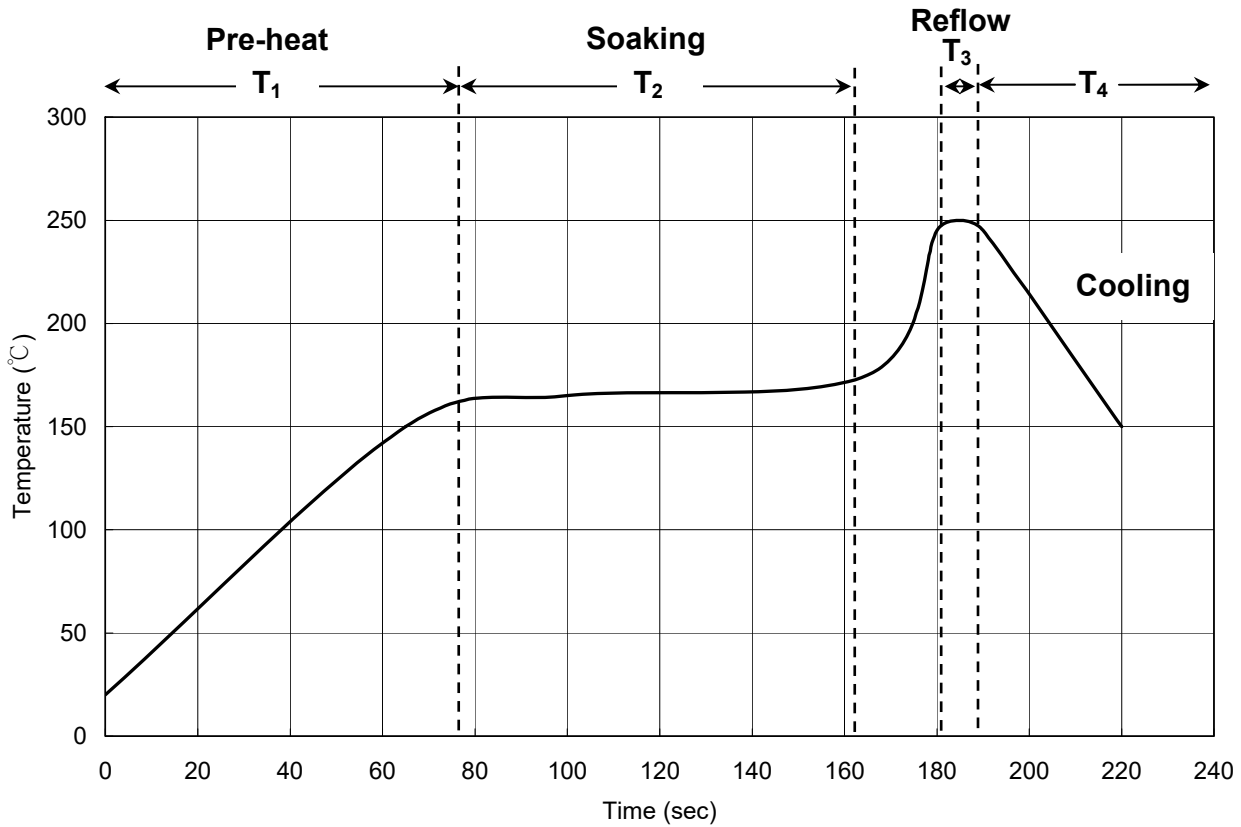
## Qualification Reliability Testing

Classification	Test Item	Test conditions	Reference Standard
Endurance Test	Operation Life	$I_F = 700\text{mA}$ $T_a = 25^\circ\text{C}$ Test Duration = 1000hrs	MIL-STD-750: 1026 MIL-STD-883: 1005 JIS C 7021: B-1
	High Temperature High Humidity Storage	$T_a = 85\pm 5^\circ\text{C}$ RH = 85±5% Test Duration = 1000hrs	MIL-STD-202: 103B JIS C 7021: B-11
	High Temperature Storage	$T_a = 105\pm 5^\circ\text{C}$ Test Duration = 1000hrs	MIL-STD-202: 1008 JIS C 7021: B10
	Low Temperature Storage	$T_a = -40\pm 5^\circ\text{C}$ Test Duration = 1000hrs	JIS C 7021: B-12
Environmental Test	Temperature Cycling	$-30^\circ\text{C} \sim 25^\circ\text{C} \sim 105^\circ\text{C} \sim 25^\circ\text{C}$ 30min 5min 30min 5min Test Duration = 10 cycle	MIL-STD-202: 107D MIL-STD-750: 1051 MIL-STD-883: 1010 JIS C 7021: A-4
	Thermal Shock	$-30\pm 5^\circ\text{C} \sim 105\pm 5^\circ\text{C}$ 30min 30min Test Duration = 10 cycle	MIL-STD-202: 107D MIL-STD-750: 1051 MIL-STD-883: 1011
	Solder Resistance	$T_{\text{sol}} = 260\pm 5^\circ\text{C}$ Dwell Time = 10sec	MIL-STD-202: 210A MIL-STD-750: 2031 JIS C 7021: A-1

Measuring Items	Symbol	Measuring Conditions	Failure Criteria
Forward voltage	$V_F$	$I_F = 700\text{mA}$	$V_F$ shift > 10%
Luminous	$I_v\%$	$I_F = 700\text{mA}$	$I_v\%$ shift > 10%

## Recommended Solder Profile

Soldering Recommended soldering conditions:



T <sub>1</sub>	Ramp up rate	1.0 ~ 3.0 °C/sec
	Pre-heat time	50 ~ 80 sec
T <sub>2</sub>	Soaking temperature	155 ~ 185 °C
	Dwell time during soaking	60 ~ 120 sec
T <sub>3</sub>	Reflow temperature	240 ~ 250 °C
	Reflow time	Max 10 sec
	Ramp up rate during reflow	1.2 ~ 2.3 °C/sec
T <sub>4</sub>	Cooling	1.0 ~ 6.0 °C/sec

Note: Suggest using Sn96Ag3Cu0.5 lead free solder.

### Cleaning

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED if necessary.

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**For the latest product information, call us or visit: [www.hplighting.com.tw](http://www.hplighting.com.tw)**

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